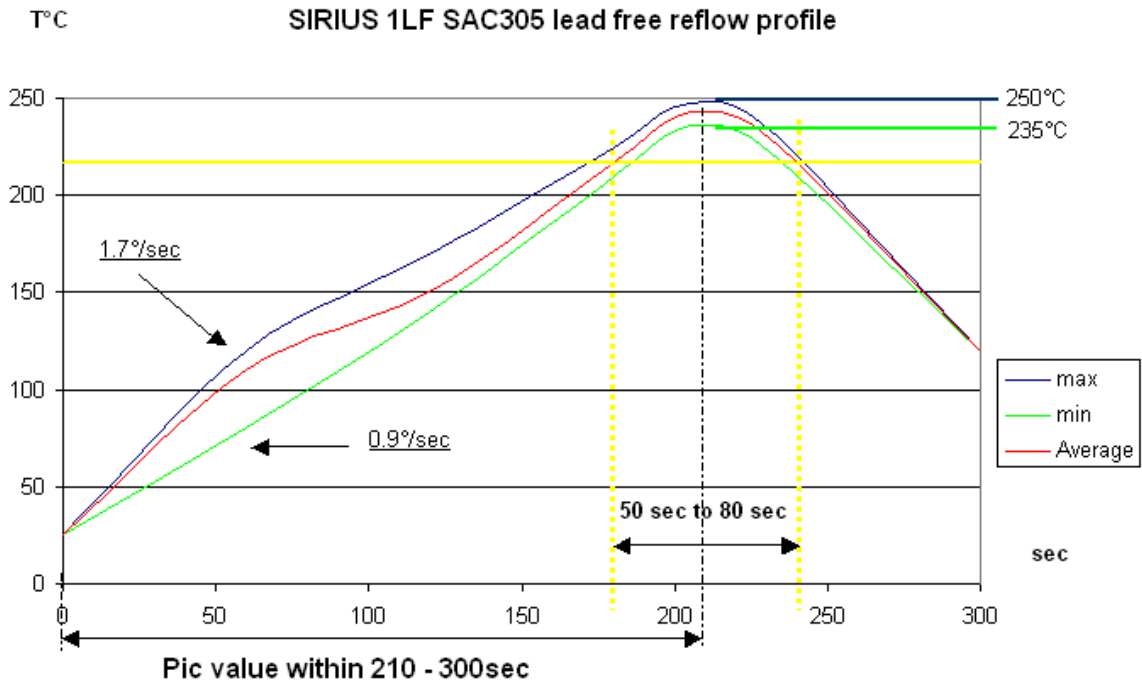




# TYPICAL REFLOW PROFILE II

## Sn96.5Ag3.0Cu0.5 Lead Free Alloy



**Typical reflow profile of solder pads across a SMT assembly using the Sn96.5Ag3.0Cu0.5 Lead Free Alloy**

*Reflow system was a Hot Air Convection reflow oven*